

Capabilities

- **Product Range :**
 - PROTOTYPES
 - DOUBLE SIDE
 - MULTILAYERS UPTO 24 LAYERS
- **Product Specifications :**

SPECIFICATIONS	STANDARAD	PROTOTYPE
MINIMUM CONDUCTOR WIDTH	5 MILS/ 0.127 MM	4 MILS/ 0.10 MM
MINIMUM CONDUCTOR SPACING	5 MILS/ 0.127 MM	4 MILS/ 0.10 MM
MINIMUM PLATED HOLE SIZE	10 MILS/ 0.25 MM	8 MILS/ 0.20 MM
MAXIMUM BOARD SIZE (ACTIVE)	610 MM X 400 MM	820 MM X 400 MM
MAXIMUM NUMBER OF LAYERS	18	24
MAXIMUM OUTER LAYER CU. THICKNESS	4 OZ (140 Micron)	6 OZ (210 Micron)
MAXIMUM INNER LAYER CU. THICKNESS	2 OZ (70 Micron)	3 OZ (105 Micron)
BOARD THICKNESS TOLERANCE	+10 %	+10 %
SMD TESTING	20 MILS/ 0.50 MM	15 MILS/ 0.38 MM

PTH-NPTH Tolerances			
PTH		NPTH	
Hole Size	Tol.	Hole Size	Tol.
0.5-3.5 mm	+/-0.10 mm	< 3.0 mm	+/- 0.10 mm
> 3.5 mm	+/-0.15 mm	> 3.0 mm	+/- 0.15 mm

PCB SIZE Tolerances	
Size	Tol.
< 150 mm	+/-0.20 mm
> 150 mm	+/-0.50 mm
Other Tolerances	
Thickness of PCB	+/- 10%
Tolerance for Track width / spacing	+/- 20%
Tolerance for Finished copper thickness (Plating in hole is considered)	> 20 micron

- **Product Finish :**

1) PROTOTYPES

LEAD FREE FINISHES

- IMMERSION SILVER
- ELECTROLESS NICKEL IMMERSION GOLD
- IMMERSION TIN
- LEAD FREE HAL

ELECTROLYTIC GOLD PLATING

HASL

CARBON PRINTING

PEELABLE MASKING

3) PRODUCT RAW MATERIAL

- FR-4, IS 400, IS 410
- RT DUROID (ROGERS)
- SPECIAL LAMINATES

2) SOLDER MASK FINISH

- PHOTO IMAGEABLE LIQUID SOLDERMASK
- SMOBC(GREEN, BLACK, RED, BLUE)
- DRY FILM SOLDERMASK